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## **Body Style:** Chip type **Reliability Indicator:** Established **Reliability Failure Rate Level In Percent:** 0.001 **Terminal Length:** 0.020 inches **Body Length:** 0.180 inches **Body Width:** 0.050 inches **Body Height:** Between 0.020 inches and 0.055 inches Schematic Diagram Designator: No common or grounded electrode (s) Insulation Resistance At Maximum Operating Temp: 10.0 megohm-microfarads **Capacitance Value Per Section:** 270.000 picofarads single section Nonderated Operating Temp: Between -55.0 degrees celsius and 125.0 degrees celsius Tempurature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius: 0.0 single section Nonderated Continuous Voltage Rating And Type Per Section: 100.0 dc single section **Tolerance Of Tempurature Coefficient Per Section In Ppm Per Deg Celsius:** -30.0/+30.0 single section **Tolerance Range Per Section:** -5.00/+5.00 percent single section **Case Material:** Ceramic Insulation Resistance At Reference Temp: 1000.0 megohm-microfarads **Dissipation Factor At Reference Tempurature In Percent:** 0.150 **Terminal Surface Treatment:** Solder **Test Data Document:**

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

## **Terminal Type And Quantity:**

2 bonding pad



## **Specification Data:**

81349-mil-c-55681/1 government specification

Shelf Life:

N/a

Unit Of Measure:

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## Demilitarization:

No

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